

IN THE CLAIMS:

Please amend claim 2 as follows:

2. (Amended) A semiconductor device comprising:

a BGA substrate having one principal plane furnished with a large number of solder balls, said solder balls constituting a ball grid array;

92 a first semiconductor chip including bumps and active regions, said bumps and active regions formed on a first side of the semiconductor chip, said bumps serving as electrodes attached to said one principal plane of said BGA substrate; and

a first chip capacitor attached to said active regions of said first semiconductor chip or to the opposite side of said active regions of said first semiconductor chip, said first chip capacitor serving to reduce power source noise.

REMARKS

This Amendment is being filed in response to the Office Action dated July 19, 2002. For the following reasons, this application should be in condition for allowance and the case passed to issue.

No new matter is introduced by this Amendment. The amendments to the specification and to claim 2 merely correct informalities. The amendment to claim 2 does not narrow the scope of the claim.